

XP-002259512

AN - 2002-150810 [20]

AP - JP20000063077 20000308

CPY - TORA

DC - A23 A26 A89 G06 L03 P84 U11

FS - CPI;GMPI;EPI

**IC - C08G73/22 ; C08K5/41 ; C08L79/04 ; G03F7/022 ; G03F7/037 ; H01L21/027 ;
H01L21/312**

**MC - A05-J02 A08-M08 A12-E07C A12-L02B2 G06-D06 G06-F03C G06-F03D L04-C05
L04-C12E**

- U11-C06A1A

PA - (TORA) TORAY IND INC

PN - JP2001249452 A 20010914 DW200220 G03F7/037 014pp

PR - JP20000063077 20000308

XA - C2002-047003

**XIC - C08G-073/22 ; C08K-005/41 ; C08L-079/04 ; G03F-007/022 ; G03F-007/037 ;
H01L-021/027 ; H01L-021/312**

XP - N2002-114477

**AB - JP2001249452 NOVELTY - Polybenzoxazole precursor comprises a polyamide
capable of converting to polybenzoxazole.**

**- DETAILED DESCRIPTION - Polybenzoxazole precursor comprises a polyamido
structure of formula (I).**

**- An INDEPENDENT CLAIM is also included for a positive mode
light-sensitive composite that contains the polybenzoxazole and an
o-quinone-naphthodiazide.**

- R1 = bivalent biphenylene;

- R2 = trivalent to hexavalent organic group;

- n = 10-100,000; and

- p = 1-4.

**- USE - The composite is used for interlayers/protective layers of
integral circuit plates and LSIs, and protective parts for other
electronic devices.**

**- ADVANTAGE - The composite has good resistance to solvents, and good
alkaline develop ability, providing precise pattern forming
capability.**

- (Dwg.0/0)

**IW - PRECURSOR POSITIVE MODE LIGHT SENSITIVE COMPOSITE COMPRISE POLYAMIDE
CAPABLE CONVERT**

**IKW - PRECURSOR POSITIVE MODE LIGHT SENSITIVE COMPOSITE COMPRISE POLYAMIDE
CAPABLE CONVERT**

NC - 001

OPD - 2000-03-08

ORD - 2001-09-14

PAW - (TORA) TORAY IND INC

**TI - Polybenzoxazole precursor, used for a positive mode light sensitiv
composite, comprises a polyamide capable of converting to
polybenzoxaz le**

A01 - [001] 018 ; P0806 H0293 D01 D22 D41 D42 F15 F34 ; P0077 ; H0293 ;

K0722 - M0000 M2005 B